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**From:** Ed Korczynski [edk@techcet.com]  
**Sent:** 1/8/2018 7:48:58 PM  
**To:** Morris, Jeff [Morris.Jeff@epa.gov]; Henry, Tala [Henry.Tala@epa.gov]  
**CC:** votaw@khlaw.com; lshonroy [lshonroy@techcet.com]; Jonas Sundqvist [jsundqvist@techcet.com]  
**Subject:** [INVITATION] 2018 CMC Conference - TSCA Update Presentation  
**Attachments:** 2018CMCC\_EPA-Abstract-Suggest1.docx; CMCC2018\_CallForPapers\_final.pdf

**Importance:** High

Hello Jeff and Tala,

We were referred to you by James Votaw (cc'd here) as the best people within US EPA to provide an update on TSCA at the Critical Materials Council (CMC) of Semiconductor Fabricators' 2018 Conference, happening April 26-27 in Phoenix, Arizona this year.

Attached is a copy of the official Call For Papers for the event. The CMC Conference Committee is very interested in hearing an update on TSCA from US EPA, and to that end the Committee asked James to draft a suggested abstract to let you know the scope of the information requested (see attached; many thanks to James). Anticipating that review/approval loops within EPA take time, we do not need a final abstract by January 15th but if possible we would like to know your general interest and availability by then.

If we can schedule a 10-15 minute phone call anytime this week to discuss possibilities (I work out of a home office in Ann Arbor, Michigan so I'm in the same time zone as D.C.), please let us know of a time convenient for you.

Continued success,  
Ed Korczynski, CMCC Co-Chair  
(408)656-4636